

| External_Type  | Material_Group   | Substances  | CAS_Number      | Mass            | Mass_Percentage_in_Leaf | Massmg            |
|----------------|------------------|---|-----------------|-----------------|-------------------------|-------------------|
| Wire           | Pure metal       | Aluminium (Al)  | 7429-90-5       | 0.01287         | 100.0                   | 0.26839           |
|                |                  |   | <b>Subtotal</b> | <b>0.01287</b>  | <b>100</b>              | <b>0.26839</b>    |
| Die            | Doped silicon    | Silicon (Si)  | 7440-21-3       | 0.08629         | 100.0                   | 1.8               |
|                |                  |   | <b>Subtotal</b> | <b>0.08629</b>  | <b>100</b>              | <b>1.8</b>        |
| Solder Wire    | Tin alloy        | Tin (Sn)  | 7440-31-5       | 0.0086          | 10.0                    | 0.17947           |
|                | Silver alloy     | Silver (Ag)   | 7440-22-4       | 0.00172         | 2.0                     | 0.03589           |
|                | Lead alloy       | Lead (Pb)   | 7439-92-1       | 0.07571         | 88.0                    | 1.57931           |
|                |                  |   | <b>Subtotal</b> | <b>0.08603</b>  | <b>100</b>              | <b>1.79467</b>    |
| Wire           | Pure metal       | Aluminium (Al)  | 7429-90-5       | 0.05147         | 100.0                   | 1.07354           |
|                |                  |   | <b>Subtotal</b> | <b>0.05147</b>  | <b>100</b>              | <b>1.07354</b>    |
| Lead Frame     | Copper alloy     | Phosphorous (P)   | 7723-14-0       | 0.00704         | 0.03                    | 0.14694           |
|                | Pure metal layer | Zinc (Zn)   | 7440-66-6       | 0.0047          | 0.02                    | 0.09796           |
|                | Pure metal layer | Tin (Sn)  | 7440-31-5       | 0.00704         | 0.03                    | 0.14694           |
|                | Pure metal layer | Iron (Fe)   | 7439-89-6       | 0.02583         | 0.11                    | 0.53877           |
|                | Pure metal layer | Copper (Cu)   | 7440-50-8       | 23.43645        | 99.81                   | 488.8594          |
|                |                  |   | <b>Subtotal</b> | <b>23.48106</b> | <b>100</b>              | <b>489.79001</b>  |
| Post-plating   | Pure metal       | Tin (Sn)  | 7440-31-5       | 0.24771         | 100.0                   | 5.167             |
|                |                  |   | <b>Subtotal</b> | <b>0.24771</b>  | <b>100</b>              | <b>5.167</b>      |
| Mould Compound | Polymer          | Tetrabromobisphenol A/Epichlorohydrin polymer           | 40039-93-8      | 2.28104         | 3.0                     | 47.58             |
|                | Polymer          | Phenol Formaldehyde resin (generic)                     | 9003-35-4       | 4.56207         | 6.0                     | 95.16             |
|                | Polymer          | Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic) | 29690-82-2      | 7.60346         | 10.0                    | 158.6             |
|                | Carbon Black     | Carbon black  | 1333-86-4       | 0.38017         | 0.5                     | 7.93              |
|                | Filler           | Misc. Silica compounds (generic)                        | 14808-60-7      | 59.30696        | 78.0                    | 1237.08           |
|                | Flame retardant  | Antimony Trioxide (Sb2O3) - cas no. 1309-64-4           | 1309-64-4       | 1.90086         | 2.5                     | 39.65             |
|                |                  |   | <b>Subtotal</b> | <b>76.03456</b> | <b>100</b>              | <b>1586</b>       |
|                |                  |   | <b>Total</b>    | <b>99.99999</b> | <b>100</b>              | <b>2085.89361</b> |

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